

Notice of References Cited

Application/Control No.

09/938,644

Applicant(s)/Patent Under
Reexamination
RUEGER, NEAL

Examiner

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Art Unit

1765

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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